

CTB Programme

Hybrids, MCM, Interconnection and Micropackaging WG

2nd Technical Presentations Day

ESTEC

27th April 2005



Hybrids, MCM, Interconnection, Micropack. WG



CTB Programme

Hybrids, MCM, Interconnection and Micropackaging WG

Agenda

- **10:00 - 10:15- Introduction** by Alberto Boetti - ESTEC TEC-QCT
- **10:15 – 10:45 - Evaluation of adhesives for flip chip assembly** by Finbarr Waldron - Tyndall National Institute - Cork - Ireland
- **11:00 – 11:30 - Investigation of flip-chip assembly technologies** by Timo Allinniemi- Patria New Technologies - Tampere - Finland
- **11:45 – 12:15 - Flip Chip for microwave applications** by Chloe Schaffauser - Alcatel Space - Toulouse - France
- **Lunch**
- **13:30 – 14:00 - State of the Art of HighTCE ceramic packages** by Olivier Gaillard - ATMEL - Grenoble - France
- **14:15 – 14:45 - Status on LTCC use for substrates and packages** by Ulisse Di Marcantonio - Alenia Spazio - L' Aquila - Italy
- **15:00 – 15:30 - Status on BGA packages mounting on PCB : Assembly and repair processes** by Nadia Wazad - EADS Astrium - Velizy - France
- **15:45 - 16:15 – Conclusions and General Discussion**